



Material Content Data Sheet



Sales Product Name		BTT6050-1EKA		Issued		21. October 2018			
MA#		MA001618312							
Package		PG-DSO-14-47		Weight*		150.20 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.990	1.32	1.32	13249	13249	
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115		
		non noble metal	zinc	7440-66-6	0.069	0.05		461	
		non noble metal	iron	7439-89-6	1.383	0.92		9211	
wire	non noble metal	non noble metal	copper	7440-50-8	56.175	37.40	38.38	374005	383792
		non noble metal	copper	7440-50-8	0.483	0.32	0.32	3215	3215
		encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1137
encapsulation	plastics	epoxy resin	-	7.859	5.23		52324		
		inorganic material	silicondioxide	60676-86-0	77.394	51.54	56.88	515283	568744
leadfinish	non noble metal	tin	7440-31-5	2.472	1.65	1.65	16456	16456	
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9789	9789	
glue	plastics	epoxy resin	-	0.125	0.08		832		
		noble metal	silver	7440-22-4	0.589	0.39	0.47	3923	4755
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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